

SOT1341-1

plastic extremely thin small outline package; no leads; 16 terminals; body 2.5 x 3.2 x 0.5 mm

8 June 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	XSON16
Package type industry code	XSON16
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-252
Mounting method type	S (surface mount)
Issue date	13-2-2013

Table 1. Package summary

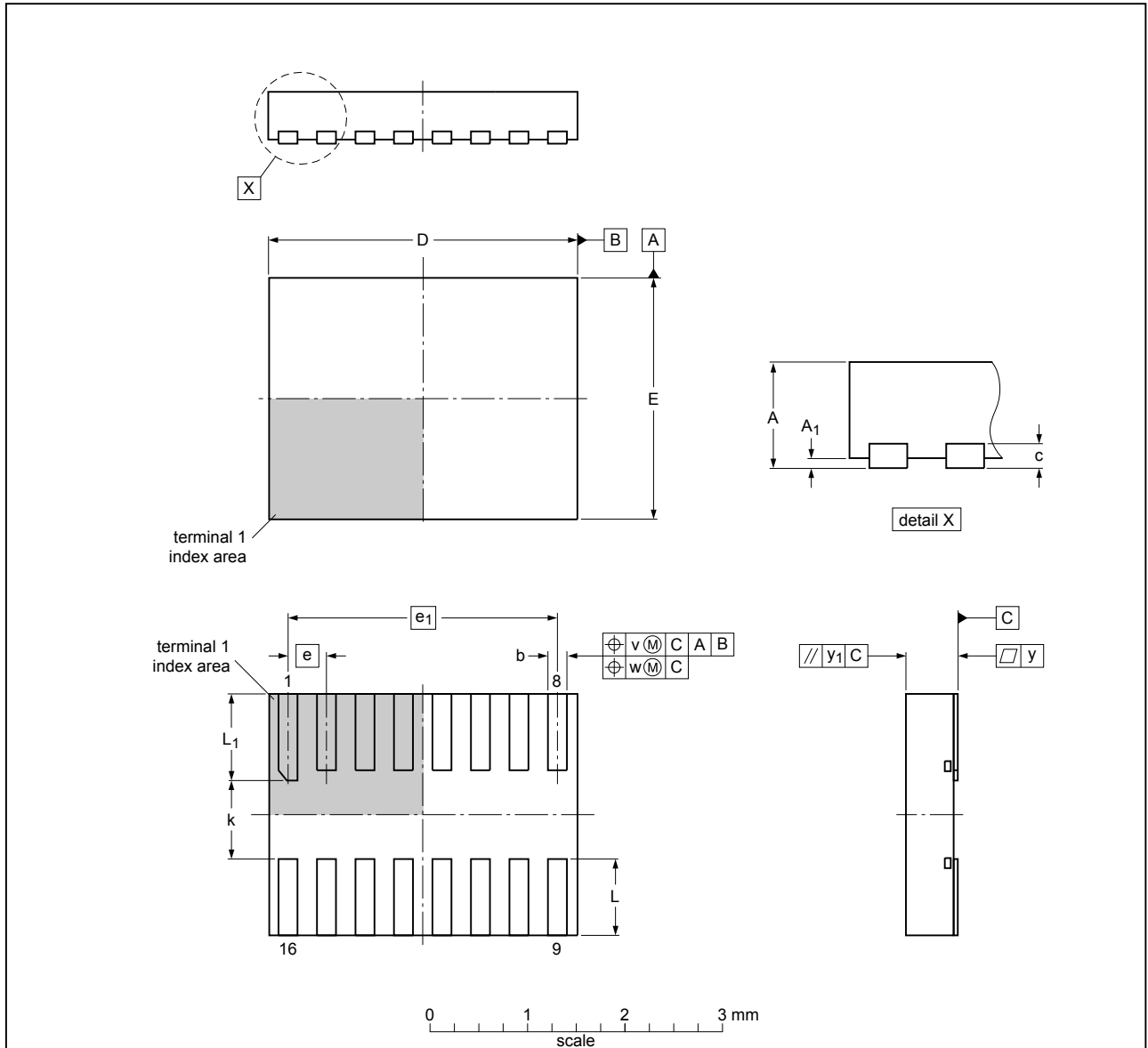
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.1	-	3.2	3.3	mm
E	package width	2.4	-	2.5	2.6	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	16	-	



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2. Package outline

XSON16: plastic extremely thin small outline package; no leads; 16 terminals; body 2.5 x 3.2 x 0.5 mm SOT1341-1



Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A	A ₁	b	c	D	E	e	e ₁	k	L	L ₁	v	w	y	y ₁
max	0.5	0.05	0.25	0.152	3.3	2.6				0.9	1.0				
nom			0.20		3.2	2.5	0.4	2.8		0.8	0.9	0.1	0.05	0.05	0.05
min		0.00	0.15	0.050	3.1	2.4			0.2	0.7	0.8				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1341-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1341-1	---	MO-252	---		-12-09-05- 13-02-13

Fig. 1. Package outline XSON16 (SOT1341-1)

3. Soldering

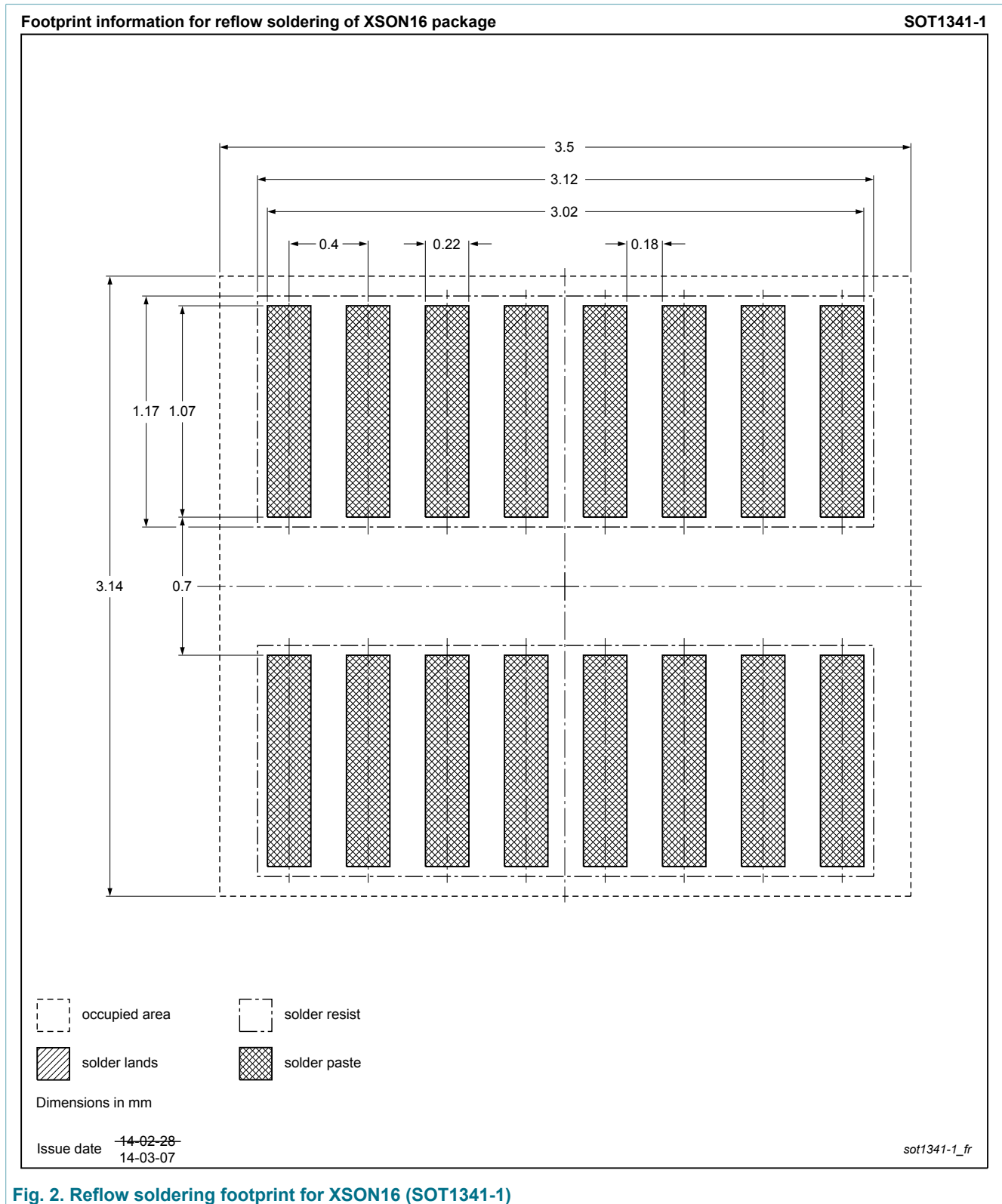


Fig. 2. Reflow soldering footprint for XSON16 (SOT1341-1)

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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Date of release: 8 June 2016
